SDLS004

D2633 JANUARY 1981 - REVISED MARCH 1988

- Parallel Register Inputs ('LS592)
- Parallel 3-State I/O: Register Inputs/ Counter Outputs ('LS593)
- Counter has Direct Overriding Load and Clear
- Accurate Counter Frequency: DC to 20 MHz

description

The 'LS592 comes in a 16-pin package and consists of a parallel input, 8-bit storage register feeding an 8-bit binary counter. Both the register and the counter have individual positive-edge-triggered clocks. In addition, the counter has direct load and clear functions. A low-going $\overline{\text{RCO}}$ pulse will be obtained when the counter reaches the hex word FF. Expansion is easily accomplished for two stages by connecting $\overline{\text{RCO}}$ of the first stage to $\overline{\text{CCKEN}}$ of the second stage. Cascading for larger count chains can be accomplished by connecting $\overline{\text{RCO}}$ of each stage to CCK of the following stage.

The 'LS593 comes in a 20-pin package and has all the features of the 'LS592 plus 3-state I/O, which provides parallel counter outputs. The tables below show the operation of the enable (CCKEN, $\overline{\text{CCKEN}}$) inputs. A register clock enable ($\overline{\text{RCKEN}}$) is also provided.

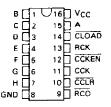
OUTPUT ENABLE CONTROL ('593 ONLY)

	G	G	A/Q _A thru H/Q _H
ı	L	L	input mode
	L	H	input mode
ı	Н	L	output mode
l	н	Н	input mode

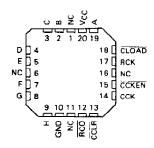
COUNTER CLOCK ENABLE CONTROL

CCKEN	CCKEN	EFFECT ON CCK
Ł	L	Enable
L	Н	Disable
н	L	Enable
Н	н	Enable

SN54LS592 . . . J OR W PACKAGE SN74LS592 . . . N PACKAGE (TOP VIEW)

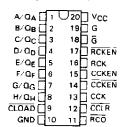


SN54LS592 . . . FK PACKAGE (TOP VIEW)

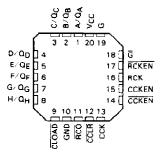


NC - No internal connection

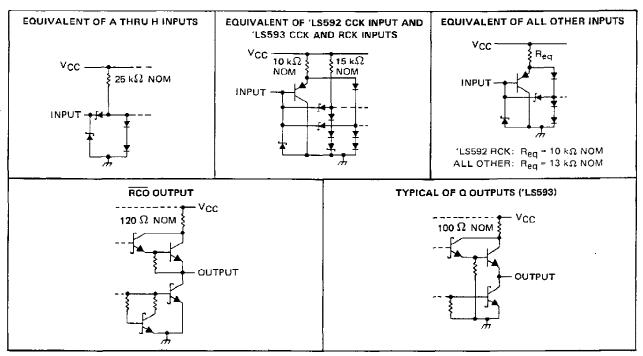
SN54LS593 . . . J OR W PACKAGE SN74LS593 . . . DW OR N PACKAGE (TOP VIEW)



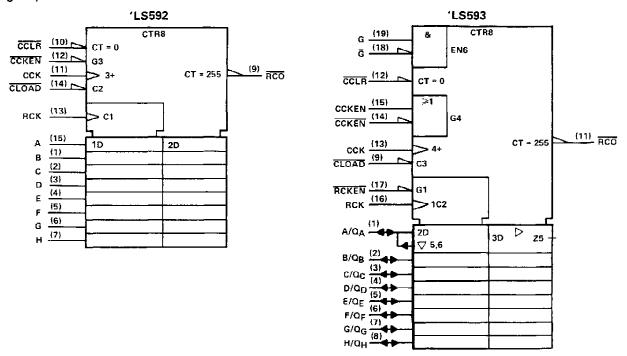
SN54LS593 . . . FK PACKAGE (TOP VIEW)



schematics of inputs and outputs

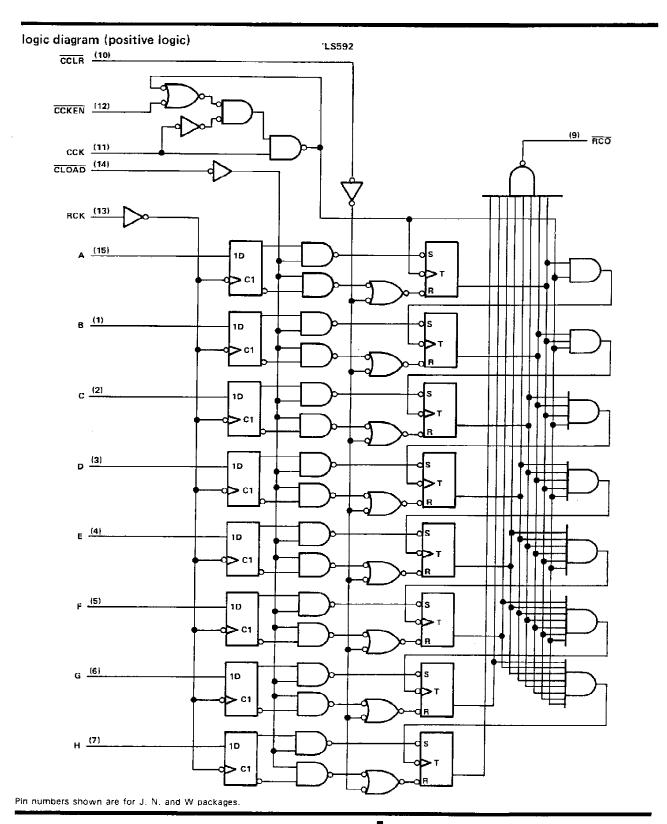


logic symbols†

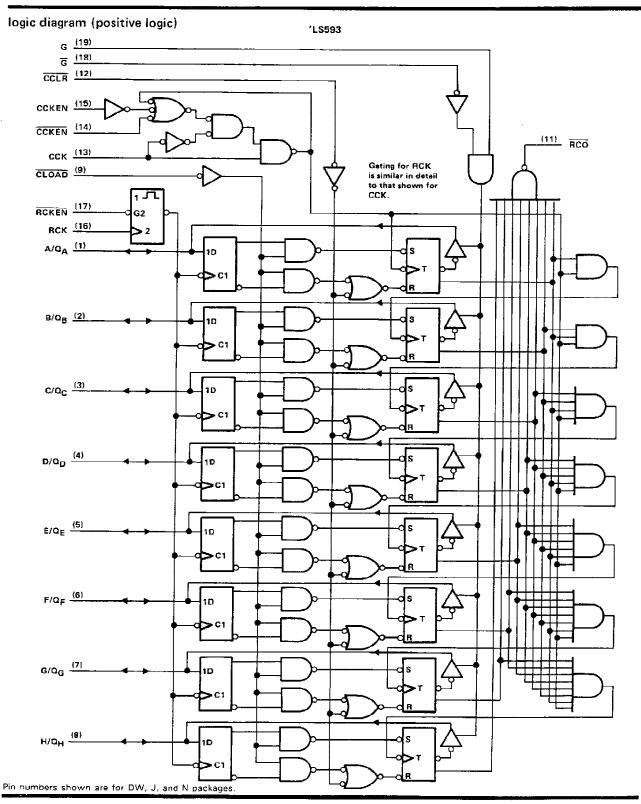


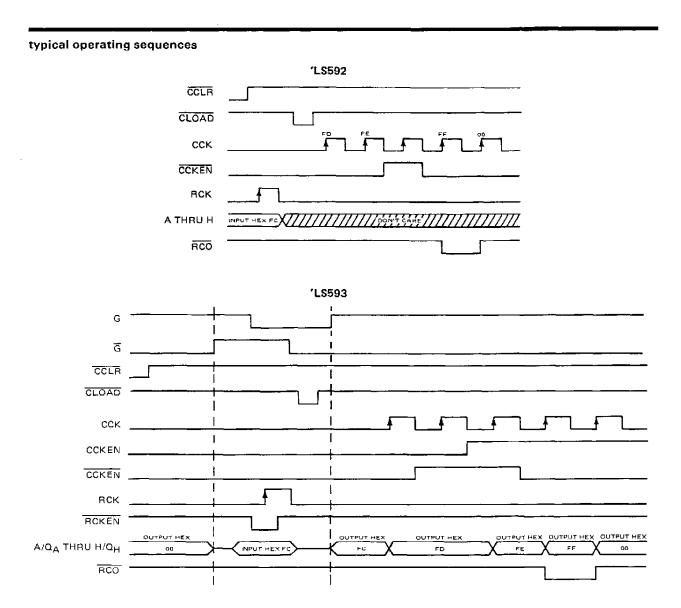
[†]These symbols are in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12. Pin numbers shown are for DW, J, N, and W packages.





SN54LS593, SN74LS593 8-BIT BINARY COUNTERS WITH INPUT REGISTERS





absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1) 7 V	
Input voltage (excluding I/O ports)	
Off-state output voltage (including I/O ports)	
Operating free-air temperature range: SN54LS592, SN54LS593 55°C to 125°C	
SN74LS592, SN74LS593 0°C to 70°C	
Storage temperature range — 65°C to 150°C	

NOTE 1: Voltage values are with respect to the network ground terminal.

recommended operating conditions

	-	······································		SN54LS	·		SN74LS	;	UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage		4.5	5	5.5	4.75	5	5.25	V
VIH	High-level input voltage		2			2			V
v_{IL}	Low-level input voltage				0.7			8.0	V
lan	High level entent en-	RCO			- 1			<u> </u>	
Іон	High-level output current	Q 'LS593 only			- 1			- 2.6	mΑ
101	Law-level output current	RCO			8			16	
'OL	Low-level bulbut current	Q 'LS593 only			12			24	mA
fcck	Counter clock frequency		0		20	0		20	MHz
^t w (CCK)	Duration of counter clock p	ulse	25			25			ns
tw (CCLR)	Duration of counter clear pu	ilse	20	•		2D			ns
tw (RCK)	Duration of register clock pe	ılse	20			20			ns
tw (CLOAD	Duration of counter load pu	Ise	40			40			ns
t _{su}	Register enable setup time	RCKEN low to RCK 1 , 'LS593	20			20			ns
	Counter enable setup time	CCKEN low, 'LS592	30			30			
t _{Su}	before CCK †	CCKEN low or CCKEN high, 'LS593	30			30			ns
		CCLR inactive before CCK 1	20			20			
^t su	Setup time	CLOAD inactive before CCK †	20			20			
'su	octop time	RCK † before CLOAD † (see Note 2)	30			30			ns
		Data A thru H before RCK †	20			20			
th	Hold time	Data A thru H after RCK †	0			0			
*11	TOTAL STITLE	All others	0			0			ns
T_A	Operating free-air temperatu	re	- 55		125	0		70	°C

NOTE 2: This time insures the data saved by RCK ↑ will also be loaded into the counter.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	DA DA 145750			s	N54LS'			N74LS	•	UNIT
	PARAMETER	TEST CONDIT	IONS	MIN	TYP‡	MAX	MIN	TYP [‡]	MAX	UNII
Vik		VCC = MIN, II = -18 m	A	İ		- 1.5			- 1.5	٧
	'LS593 Q	V _{CC} = MIN, V _{IH} = 2 V,	I _{OH} = -1 mA	2.4	3.2					
Vон		V _{II} = MAX	I _{OH} = -2.6 mA	<u> </u>			2.4	3.1		٧
	RCO	AIT - MAY	I _{OH} = -1 mA	2.4	3.2		2.4	3.2		
	'LS593 Q		I _{OL} = 12 mA		0.25	0.4		0.25	0.4	
VOL	20000 0	V_{CC} - MIN, V_{IH} = 2 V,	I _{OL} = 24 mA			_		0.35	0.5	v
TUL	RCO	V _{IL} = MAX	IOL = 8 mA		0.25	0.4		0.25	0.4	
			IOL = 16 mA					0.35	0.5	
^I OZH	'LS593 Q	$V_{CC} = MAX$, $V_{IH} = 2 V$,	V _{IL} = MAX,			20			20	μА
'02H	20000 (2	V _O = 2.7 V								
lozL	′LS593 Q	V _{CC} = MAX, V _{IH} - 2 V,	$V_{IL} = MAX$			-0.4			-0.4	mΑ
'UZL	10000 0	V _O = 0.4 V		<u> </u>		• • • • • • • • • • • • • • • • • • • •				
11	'LS593 Q	V _{CC} - MAX	V _I = 5.5 V			0.1			0.1	mΑ
"I	Others		V _I = 7 V			0.1			0.1	
^t iH		$V_{CC} = MAX$, $V_{I} = 2.7 V$				20			20	μА
	CCK					-0.8			-0.8	
	RCK LS592					-0.2			-0.2	
IIL	'LS593	$V_{CC} = MAX$, $V_I = 0.4 V$				-0.B			- O.8	mA
	A thru H					-0.4			-0.4	
	Others					-0.2			-0.2	
los⁵	'LS593 Q	$V_{CC} = MAX, V_{C} = 0 V$		- 30		- 130	- 30		- 130	mA
.03	RCO			- 20		- 100	- 20		- 100	
	'LS592 CCH				40	60		40	60	
	ICCL	V _{CC} = MAX,			40	60		40	60	
ICC	<u> Іссн</u>	All possible inputs grounded,			47	70		47	70	mΑ
	'LS593 I _{CCL}	All outputs open			53	80		53	80	
	l (ccz				57	85	İ	57	85	

Teor conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

 $^{^{\}ddagger}$ All typical values are at V_{CC} = 5 V, T_A = 25 °C.

Not more than one output should be shorted at a time and the duration of the short-circuit should not exceed one second.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$, (see note 3)

•	FROM	то			T	'LS592			'LS593		UNIT
PARAMETER	(INPUT)	(OUTPUT)	TEST COND	ITIONS	MIN	TYP	MAX	MIN	TYP	MAX	CIVIT
fmax	ССК	RCO	$R_L = 1 k\Omega$,	CL = 30 pF	20	35		20	35		MHz
¹₽LH	CCK1	O.			T .				14	21	ns
tPHL	CCK1	Q							26	39	nş
īРLН	CLOAD +	Q	$R_L = 667 \Omega$,						34	51	ns
tpHL	CLOAD +	Ω							28	42	ns
tPHL	CCLR +	۵		Cլ = 45 pF					25	38	ns
^t PZH	G t	Q	1						31	47	ns
[†] PZL	G t	Q							27	40	ns
^t PZH	G↓	Q							29	45	ns
tPZL.	G ↓	a							31	47	ns
tPHZ	G I	a							33	50	ns
^t PL Z	G↓	a	, aa	0 5 5					35	52	ns
tpH2	<u>G</u> 1	a	RL = 667 Ω,	C[=5p⊦					26	39	ns
^t PLZ	Ğt	Q.	1						28	42	ns
[†] PLH	CCK t	RÇO				15	23		14	21	ns
[†] PHL	CCK 1	RCO	1			20	30		20	30	ns
tPLH	CLOAD +	ACO	R _L = 1 kΩ,	$C_L = 30 pF$		31	47		31	47	ns
tpHL.	CLOAD :	RCO				27	41		27	41	ns
¹₽ĿH	CCLR +	ACO	1			30	45		30	45	ns
tPLH	RCK 1	RCO	ŘL = 1 kΩ;	C _L = 30 pF		35	53	<u> </u>	42	63	ns
tPHL.	RCK †	RCO	CLOAD = L			30	45		33	50	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.





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PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
5962-8762101EA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8762101EA SNJ54LS592J	Samples
5962-8762101FA	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8762101FA SNJ54LS592W	Samples
5962-8762101FA	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8762101FA SNJ54LS592W	Samples
SN54LS592J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54LS592J	Samples
SN54LS592J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54LS592J	Samples
SN54LS593J	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54LS593J	Samples
SN54LS593J	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54LS593J	Samples
SN74LS592D	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS592	Samples
SN74LS592D	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS592	Samples
SN74LS592N	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS592N	Samples
SN74LS592N	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS592N	Samples
SN74LS592NSR	ACTIVE	SO	NS	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS592	Samples
SN74LS592NSR	ACTIVE	SO	NS	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS592	Samples
SN74LS593DW	ACTIVE	SOIC	DW	20	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS593	Samples
SN74LS593DW	ACTIVE	SOIC	DW	20	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS593	Samples
SN74LS593DWR	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS593	Samples
SN74LS593DWR	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS593	Samples
SN74LS593N	ACTIVE	PDIP	N	20	20	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS593N	Samples



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			-		-						
Orderable Device	Status	Package Type	Package	Pins	Package	Eco Plan	Lead finish/	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	Ball material	(3)		(4/5)	
							(6)				
SN74LS593N	ACTIVE	PDIP	N	20	20	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS593N	Samples
SNJ54LS592J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8762101EA SNJ54LS592J	Samples
SNJ54LS592J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8762101EA SNJ54LS592J	Samples
SNJ54LS592W	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8762101FA SNJ54LS592W	Samples
SNJ54LS592W	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8762101FA SNJ54LS592W	Samples
SNJ54LS593J	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS593J	Samples
SNJ54LS593J	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS593J	Samples

(1) The marketing status values are defined as follows: **ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

PACKAGE OPTION ADDENDUM

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(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54LS592, SN54LS593, SN74LS592, SN74LS593:

Catalog: SN74LS592, SN74LS593

Military: SN54LS592, SN54LS593

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS592NSR	so	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74LS593DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1

PACKAGE MATERIALS INFORMATION

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS592NSR	SO	NS	16	2000	356.0	356.0	35.0
SN74LS593DWR	SOIC	DW	20	2000	367.0	367.0	45.0

PACKAGE MATERIALS INFORMATION

www.ti.com 9-Aug-2022

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
5962-8762101FA	W	CFP	16	1	506.98	26.16	6220	NA
SN74LS592D	D	SOIC	16	40	507	8	3940	4.32
SN74LS592N	N	PDIP	16	25	506	13.97	11230	4.32
SN74LS592N	N	PDIP	16	25	506	13.97	11230	4.32
SN74LS593DW	DW	SOIC	20	25	507	12.83	5080	6.6
SN74LS593N	N	PDIP	20	20	506	13.97	11230	4.32
SNJ54LS592W	W	CFP	16	1	506.98	26.16	6220	NA

14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP2-F16



14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.





SOIC



- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
- 5. Reference JEDEC registration MS-013.



SOIC



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOIC



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.





SOP



- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing
- per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.



SOF



NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOF



NOTES: (continued)

- 7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 8. Board assembly site may have different recommendations for stencil design.



D (R-PDS0-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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